

## Product Summary

- $V_{DS} = 60V, I_D = 0.34A$
- $R_{DS(on)} < 1.5\Omega @ V_{GS} = 10V$
- $R_{DS(on)} < 1.6m\Omega @ V_{GS} = 4.5V$

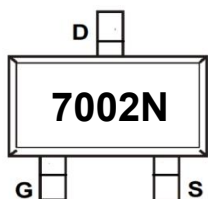
## Features

- Advanced Trench Technology
- RoHS and Reach Compliant
- Halogen and Antimony Free
- Moisture Sensitivity Level 3

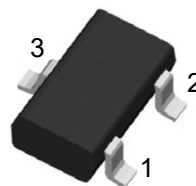
## Application

- Battery Operated Systems
- Direct Logic-level Interface:TTL/CMOS
- Solid-State Relays

## Marking Code



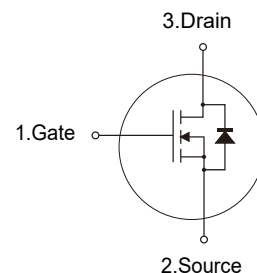
## SOT-323



(Top View)

Pin	Description
1	Gate
2	Source
3	Drain

## Schematic Diagram



## Absolute Maximum Ratings

(Ta=25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	0.34	A
Drain Current-Pulsed <sup>Note1</sup>	$I_{DM}$	1.4	A
Maximum Power Dissipation	$P_D$	0.28	W
Junction Temperature	$T_J$	150	°C
Storage Temperature Range	$T_{STG}$	-55 to +150	°C

## Thermal Characteristics

Thermal Resistance,Junction-to-Ambient <sup>Note2</sup>	$R_{\theta JA}$	450	°C/W
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## Electrical Characteristics

(T<sub>J</sub>=25°C unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Typ	Max	Units
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$		60			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	$V_{(BR)DSS}/T_J$				71		mV/°C
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{GS} = 0\text{ V},$ $V_{DS} = 60\text{ V}$	$T_J = 25^\circ\text{C}$			1.0	$\mu\text{A}$
			$T_J = 150^\circ\text{C}$			15	$\mu\text{A}$
		$V_{GS} = 0\text{ V},$ $V_{DS} = 50\text{ V}$	$T_J = 25^\circ\text{C}$			100	nA
			$T_J = 150^\circ\text{C}$			10	$\mu\text{A}$
Gate-to-Source Leakage Current	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$				$\pm 10$	$\mu\text{A}$
		$V_{DS} = 0\text{ V}, V_{GS} = \pm 10\text{ V}$				450	nA
		$V_{DS} = 0\text{ V}, V_{GS} = \pm 5.0\text{ V}$				150	nA

**ON CHARACTERISTICS** (Note 2)

Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = 250 μA		1.0		2.5	V
Negative Threshold Temperature Coefficient	V <sub>GS(TH)</sub> /T <sub>J</sub>				4.0		mV/°C
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 500 mA			1.19	1.6	Ω
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 200 mA			1.33	2.5	
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> = 5 V, I <sub>D</sub> = 200 mA			530		mS

**CHARGES AND CAPACITANCES**

Input Capacitance	C <sub>ISS</sub>	V <sub>GS</sub> = 0 V, f = 1 MHz, V <sub>DS</sub> = 20 V		24.5			pF
Output Capacitance	C <sub>OSS</sub>			4.2			
Reverse Transfer Capacitance	C <sub>RSS</sub>			2.2			
Total Gate Charge	Q <sub>G(TOT)</sub>	V <sub>GS</sub> = 4.5 V, V <sub>DS</sub> = 10 V; I <sub>D</sub> = 200 mA		0.7			nC
Threshold Gate Charge	Q <sub>G(TH)</sub>			0.1			
Gate-to-Source Charge	Q <sub>GS</sub>			0.3			
Gate-to-Drain Charge	Q <sub>GD</sub>			0.1			

**SWITCHING CHARACTERISTICS, V<sub>GS</sub> = V** (Note 3)

Turn-On Delay Time	t <sub>d(ON)</sub>	V <sub>GS</sub> = 10 V, V <sub>DD</sub> = 25 V, I <sub>D</sub> = 500 mA, R <sub>G</sub> = 25 Ω		12.2			ns
Rise Time	t <sub>r</sub>			9.0			
Turn-Off Delay Time	t <sub>d(OFF)</sub>			55.8			
Fall Time	t <sub>f</sub>			29			

**DRAIN-SOURCE DIODE CHARACTERISTICS**

Forward Diode Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 200 mA	T <sub>J</sub> = 25°C		0.8	1.2	V
			T <sub>J</sub> = 85°C		0.7		

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%
2. Switching characteristics are independent of operating junction temperatures

Typical Characteristic Curves

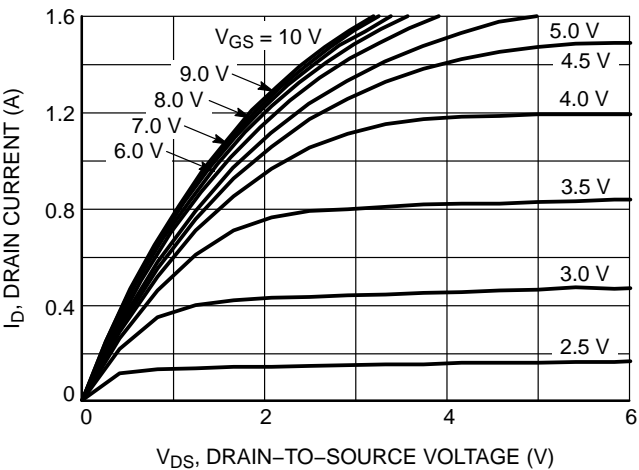


Figure 1. On-Region Characteristics

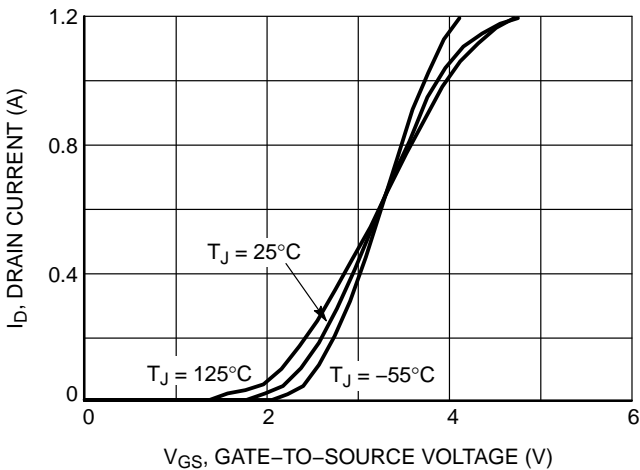


Figure 2. Transfer Characteristics

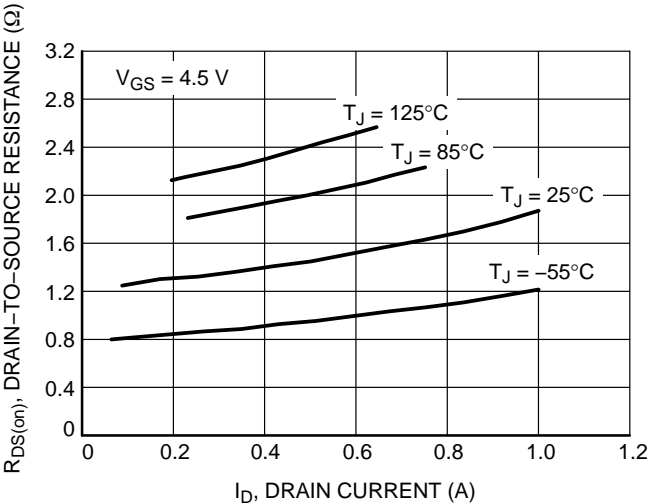


Figure 3. On-Resistance vs. Drain Current and Temperature

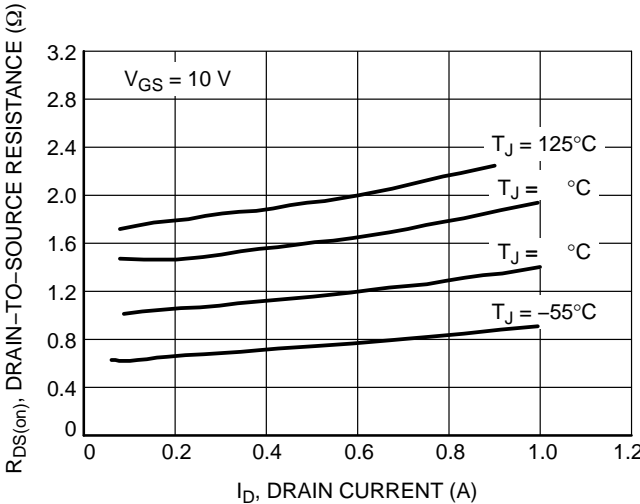


Figure 4. On-Resistance vs. Drain Current and Temperature

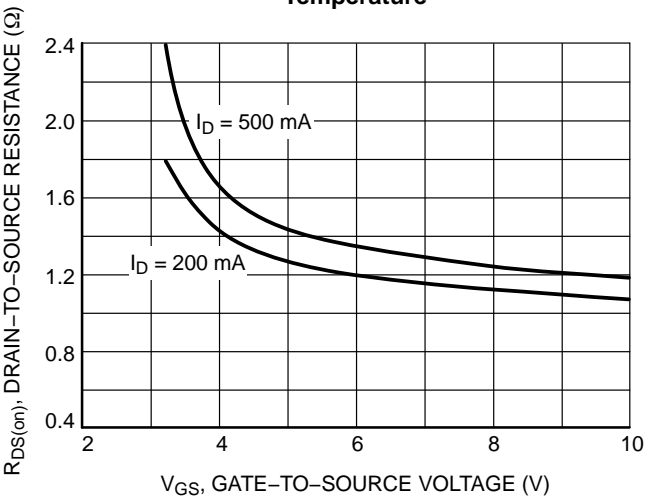


Figure 5. On-Resistance vs. Gate-to-Source Voltage

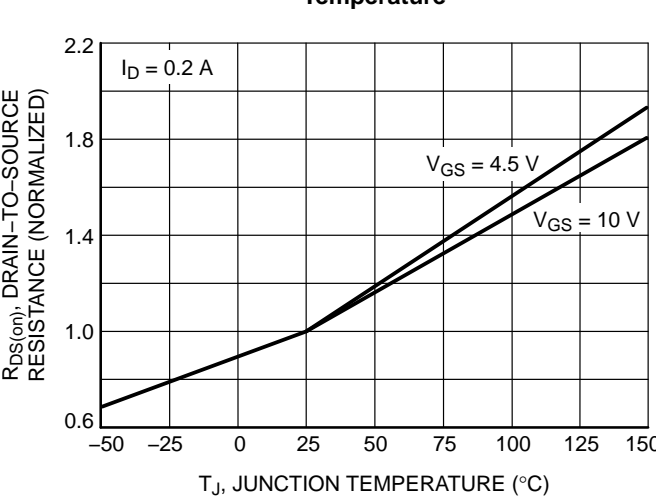


Figure 6. On-Resistance Variation with Temperature

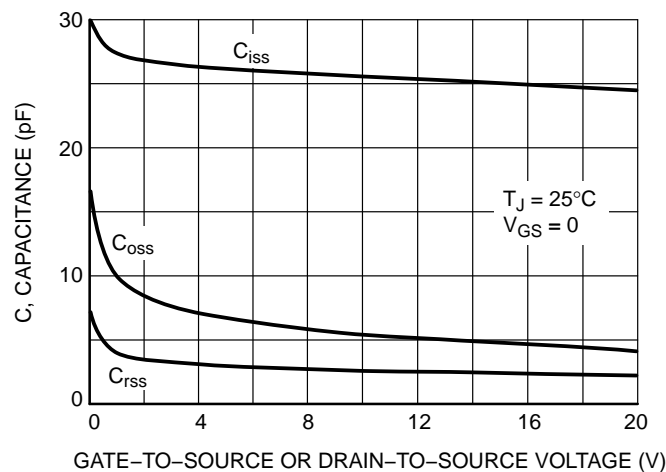


Figure 7. Capacitance Variation

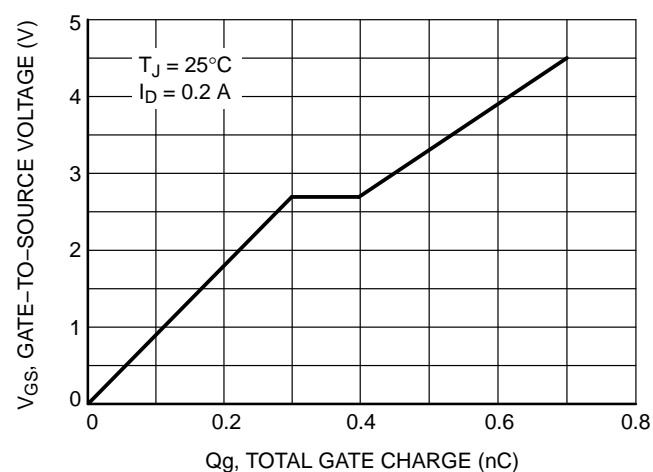


Figure 8. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

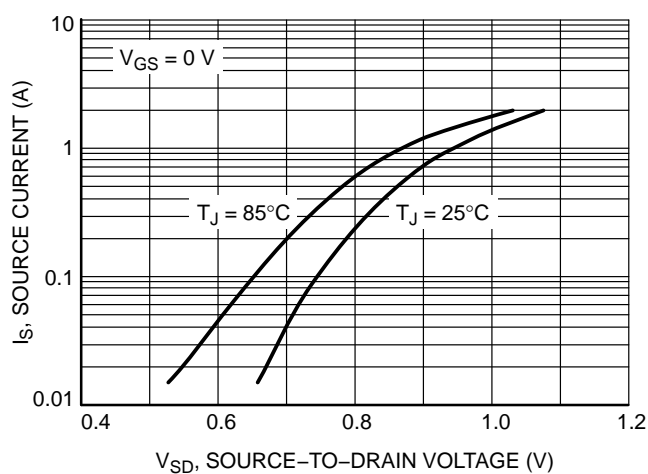


Figure 9. Diode Forward Voltage vs. Current

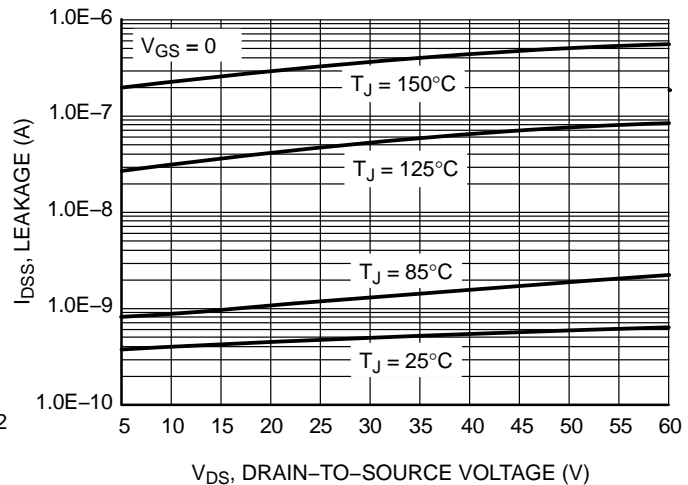
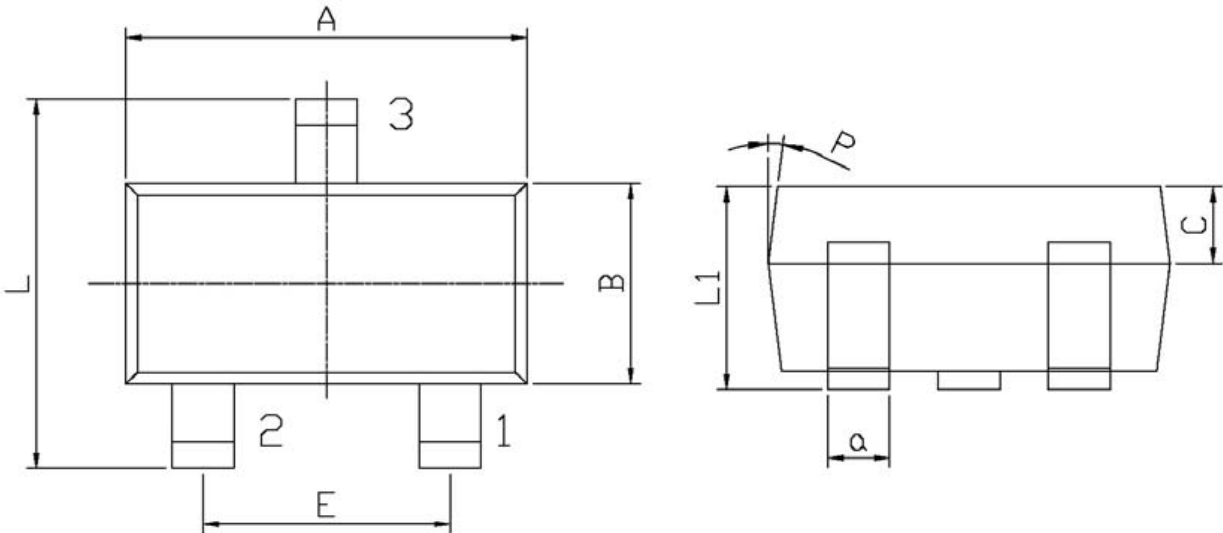


Figure 10. Drain-to-Source Leakage Current vs. Voltage

Package Outline

SOT-323

Dimensions in mm



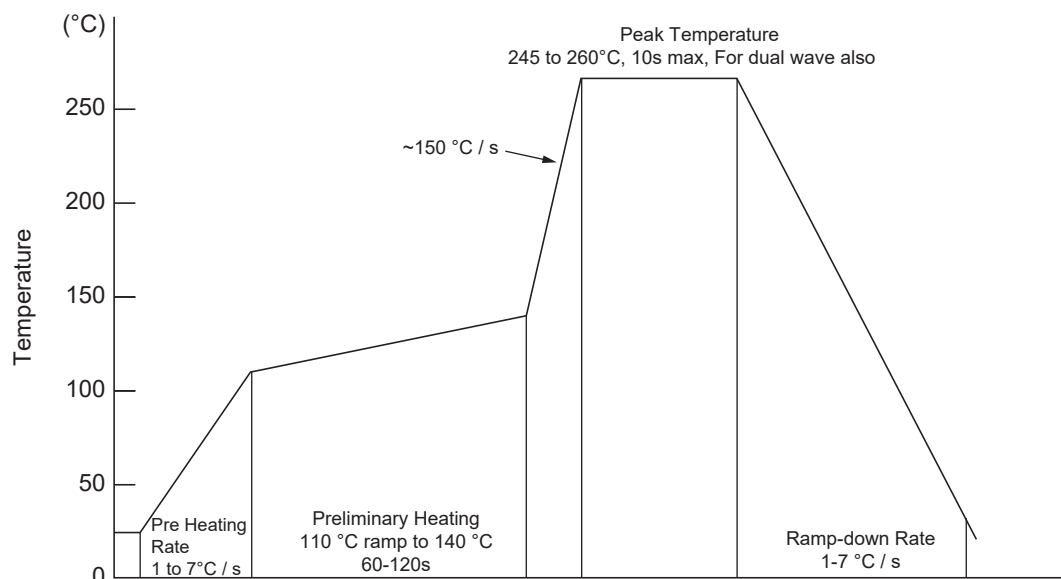
Symbol	Dimensions		Symbol	Dimensions	
	Min.	Max.		Min.	Max.
A	1.95	2.35	C	0.30	0.50
L	2.00	2.20	L1	0.85	1.15
E	1.20	1.40	a	0.20	0.40
B	1.15	1.35	P	7°	

Ordering Information

Device	Package	Shipping
TN7002NSI	SOT-323	3,000PCS/Reel&7inches

## Conditions of Soldering and Storage

## ◆ Wave Soldering



## ◆ Conditions of hand soldering

- Temperature: 360°C
- Time: 3s max.
- Times: one time

## ◆ Storage conditions

- **Temperature**  
5 to 40°C
- **Humidity**  
30 to 80% RH
- **Recommended period**  
One year after manufacturing

## Contact Information

TANI website: <http://www.tanisemi.com> Email: [tani@tanisemi.com](mailto:tani@tanisemi.com)

For additional information, please contact your local Sales Representative.



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